



Material Content Data Sheet



Sales Product Name		BTS50020-1TAD		Issued		25. January 2018		
MA#		MA001475554						
Package		PG-TO263-7-10		Weight*		1555.11 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	9.752	0.63	0.63	6271	6271
leadframe	inorganic material	phosphorus	7723-14-0	0.247	0.02		159	
	non noble metal	iron	7439-89-6	0.823	0.05		530	
wire	non noble metal	copper	7440-50-8	822.375	52.87	52.94	528823	529512
	non noble metal	aluminium	7429-90-5	10.836	0.70	0.70	6968	6968
encapsulation	organic material	carbon black	1333-86-4	8.395	0.54		5398	
	plastics	epoxy resin	-	92.342	5.94		59380	
leadfinish	inorganic material	silicondioxide	60676-86-0	458.914	29.51	35.99	295101	359879
	non noble metal	tin	7440-31-5	12.163	0.78	0.78	7821	7821
plating	inorganic material	phosphorus	7723-14-0	0.007	0.00		5	
	non noble metal	nickel	7440-02-0	2.941	0.19	0.19	1891	1896
glue	plastics	Polyimide	26023-21-2	0.198	0.01	0.01	128	128
solder	non noble metal	tin	7440-31-5	0.107	0.01		69	
	noble metal	silver	7440-22-4	0.134	0.01		86	
heatspreader	non noble metal	lead	7439-92-1	5.112	0.33	0.35	3287	3442
	inorganic material	phosphorus	7723-14-0	0.039	0.00		25	
	non noble metal	iron	7439-89-6	0.131	0.01		84	
	non noble metal	copper	7440-50-8	130.589	8.40	8.41	83974	84083
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com